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04-15-2005

Attorney Docket U 015710-8

RE



EET

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To the Honorable Commissioner of Patents and Trademarks, please receive the attached original documents or copy thereof.

1. Name of conveying party(ies):

1. MIN-LUNG HUANG
- 2.
- 3.

Additional name(s) of conveying party(ies) attached?

☐ Yes ☒ No

2. Name and address of receiving party (ies):

Name: ADVANCED SEMICONDUCTOR
ENGINEERING INC.Address: 26 CHIN 3RD ROAD,
NANTZE EXPORT PROCESSING ZONE,
KAOHSIUNG, TAIWAN, R.O.C.

3. Nature of conveyance:

- | | |
|--|--|
| <input checked="" type="checkbox"/> Assignment | <input type="checkbox"/> Merger |
| <input type="checkbox"/> Security Agreement | <input type="checkbox"/> Change of Name |
| <input type="checkbox"/> Other _____ | <input type="checkbox"/> Change of Address |

Additional name(s) & addresses(es) attached?

☐ Yes ☒ NoExecution Date(s):
1. July 1, 2004
2.
3.

4. Application number(s) or patent number(s)

☒ Being filed together with a new application.☐ Patent Application
No.(s):☐ Patent No.(s):Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Clifford J. Mass
Address: Ladas & Parry LLP
26 West 61st Street
New York, N.Y. 10023

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41) \$ _____ @ \$40.00 each

☐ Check Enclosed☒ Authorized to be charged in whole or in part to:

8. Deposit account number: 12-0425

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9. Signature:

Clifford J. Mass
Name of Person Signing

Signature

APRIL 5, 2006
Date

Total number of pages including coversheet, attachments, and documents:

3

04/14/2005 ECDOPER 00000179 11099172

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(40.00 DP)

(Cover Sheet for Assignment Accompanying New Patent Application—page 2 of 2) 4-2.3a

PATENT
REEL: 016453 FRAME: 0353

USA Patent Appln.
Sole or Joint

ASSIGNMENT

In consideration of the sum of Ten Dollars (\$10.00) and other good and valuable consideration paid to each of the undersigned, to wit:

Insert Name(s)
of Inventor(s)

(1) Min-Lung Huang (5) _____
(2) _____ (6) _____
(3) _____ (7) _____
(4) _____ [] x box if continued on back

the receipt and sufficiency of which are hereby acknowledged by the undersigned who at the request of, hereby sell(s), assign(s) and transfer(s) unto:

Insert Name
of Assignee
and Address

ADVANCED SEMICONDUCTOR ENGINEERING, INC.
26 Chin 3rd Road, Nantze Export Processing Zone Kaoshiung, Kaoshiung
Taiwan, R.O.C.

(hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100, in and to the invention known as

Title of
Invention

METHOD FOR FORMING A REDISTRIBUTION LAYER IN A
WAFER STRUCTURE

NOTE -> -> ->
(use only
when appln.
signed on
same date)

for which an application for Letters Patent of the United States of America has been executed even date herewith by the undersigned, and in and to any and all divisions, continuations, substitutes, and reissues thereof; and all resulting patents; and the undersigned hereby authorize(s) and request(s) the United States Commissioner or Patents and Trademarks to issue said Letters Patent to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree(s) that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree(s) to testify and execute any papers for ASSIGNEE, its successors, assigns and legal representatives, deemed essential by ASSIGNEE to ASSIGNEE'S full protection and title in and to the invention hereby transferred.

Please sign
concurrently
with Declaration

Signed on the date(s) indicated beside our signatures.

INVENTOR(S)		DATE SIGNED	
1)	<u>Huang Min-Lung</u> Name: Min-Lung Huang	<u>7/1/04</u>	
2)	Name: _____		
3)	Name: _____		
4)	Name: _____		
5)	Name: _____		
6)	Name: _____		
7)	Name: _____		

FOR ADDITIONAL INVENTORS check box 1, 2 and continue on separate side

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PATENT
REEL: 016453 FRAME: 0354